

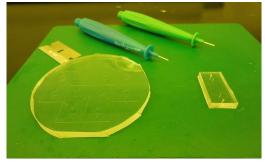
Microfluidic/Microfabrication Facility, Harvard Medical School

PROCEDURES FOR BONDING PDMS

Microfluidics Core Facility, Harvard Medical School

Sample cleaning

1. Punch the through-holes onto patterned PDMS slab for tubing connection.



2. Clean the PDMS surface with Isopropanol. Wipe the surface gently with foam-cotton swabs. Rinse in D.I. water and blow dry with compressed nitrogen.

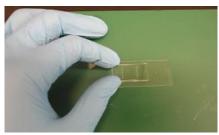
Dry-run to set the bonding parameters for plasma etcher

- 3. Check that the inlet valves of O₂ and Ni are open (on the wall).
- 4. Turn on the vacuum pump.
- 5. Turn the **main power** on (red bottom).
- Switch to open vacuum toggle switch (labeled as VAC in front panel). And check the throttle
 pressure on the display and wait until the pressure stabilizes 0.100-0.350 torr (waiting time of
 ~15min).
- 7. Open gas 2 toggle switch (oxygen) for 2-4 mins.
- 8. Adjust and stabilize the pressure at approximately 0.170-0.350 torr.
- 9. Turn on the RF power switch and set the power at 100-150 Watts.
- 10. Turn off the RF power.
- 11. Turn off gas 2.
- 12. Turn off vacuum.
- 13. Switch to open **vent** toggle switch.
- 14. Wait until the door can be opened and turn off the vent.

Bonding Process

- 15. Load your samples. The surfaces needing treatment have to be face-up.
- 16. Turn on the vacuum toggle switch.
- 17. Turn on the gas 2 switch.
- 18. Turn on the **RF power** toggle switch.
- 19. Expose the samples to plasma treatment for 10sec.

- 20. Turn off the RF power.
- 21. Turn off the gas 2.
- 22. Turn off the **vacuum** toggle switch.
- 23. Switch to open vent switch.
- 24. Wait until the pressure reaches 1torr and the door can be opened.
- 25. Turn off the **vent** switch.
- 26. Take the samples out and bond them in within 5 mins.



- 27. Put the bonded samples in oven of 65-80 degrees for 20mins in order to enhance bonding.
- 28. Test the bonding strength, trying to peel the layer off.



Front panel plasma etcher

